

# 3.2x1.6 x1.8mm 850nm Infrared Dome Lens Chip LED

#### OSI3120641E

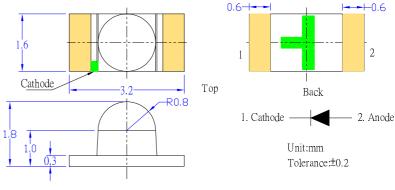
#### **■Features**

- · Single chip
- Compact package outline
  (L x W x T) of 3.2mm x 1.6mm x1.8mm
- Compatible to IR reflow soldering.
- High power output of min. 5mW/Sr@20mA

# **■**Applications

- · Automatic Control System
- Photo Detector
- · Computer I/O Peripheral

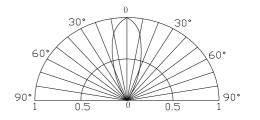
# **Outline Dimension**



# ■Absolute Maximum Rating

Item	Symbol	Value	Unit
DC Forward Current	$I_{\mathrm{F}}$	75	mA
Pulse Forward Current*	$I_{\mathrm{FP}}$	100	mA
Reverse Voltage	$V_R$	5	V
Power Dissipation	$P_{D}$	120	mW
Operating Temperature	Topr	-40 ~ +85	$^{\circ}\!\mathbb{C}$
Storage Temperature	Tstg	-40~ +85	$^{\circ}\!\mathbb{C}$
Lead Soldering Temperature	Tsol	260°C/5sec	-

# Directivity



# **■**Electrical -Optical Characteristics

Item	Symbol	Conditio n	Min.	Тур.	Max.	Unit
DC Forward Voltage	$V_{F}$	I <sub>F</sub> =20mA	-	1.3	1.7	V
DC Reverse Current	$I_R$	V <sub>R</sub> =5V	-	1	10	μΑ
Peak Wavelength	$\lambda_p$	I <sub>F</sub> =20mA	-	850	-	nm
Radiant Intensity	Ie	I <sub>F</sub> =20mA	5	10	-	mW/Sr
50% Power Angle	2θ1/2	I <sub>F</sub> =20mA	-	35	-	deg

Note: \* Vf tolerance: ±0.05V

# **LED & Application Technologies**





(Ta=25°C)

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http://www.optosupply.com VER A.1.2

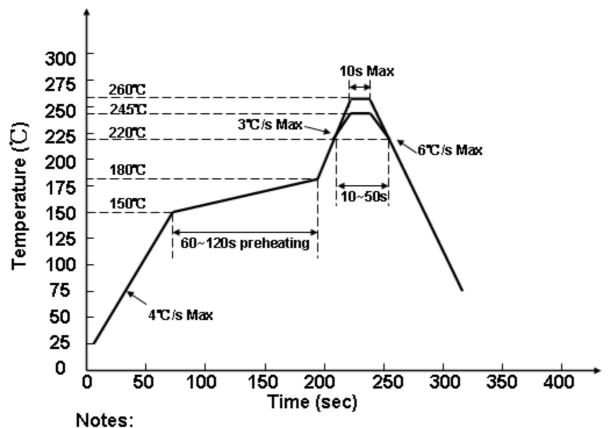
<sup>\*</sup>Pulse width Max 0.1ms, Duty ratio max 1/10

<sup>\*</sup> Dominant wavelength tolerance: ±1nm

<sup>\*</sup> Luminous intensity is NIST reading. Luminous intensity tolerance:  $\pm 10\%$ 

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#### **■** For Lead Free Solder



We recommend the soldering temperature 245 $\pm$ 5 $^{\circ}$ C; The maximum temperature should be limited to 260  $^{\circ}$ C.







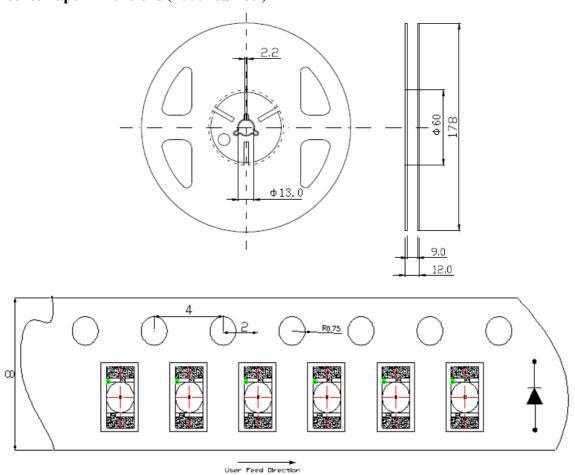




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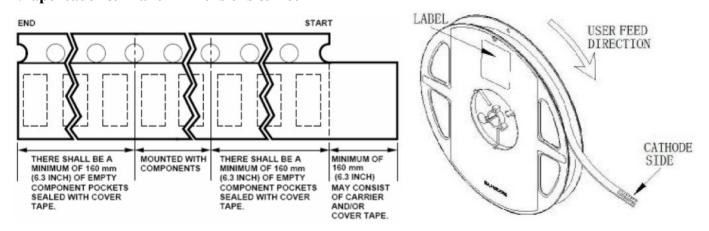
## **■**Packaging

# 1. Reel & Tape Dimensions (2000Pcs/Reel)



Notes: All dimensions are in millimeters

# 2. Tape leader & Trailer Dimensions & Reel



# **LED & Application Technologies**





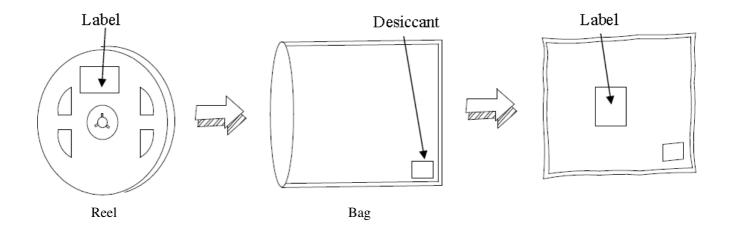




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## 3. Bag Packaging



#### Cautions:

- 1. After open the package, the LED's floor life is 4 Weeks under 30°C or less and 60%RH or less(MSL:2a).
- 2. Heat generation must be taken into design consideration when using the LED.
- 3. Power must be applied resistors for protection, over current would be caused the optic damage to the devices and wavelength shift.
- 4. Manual tip solder may cause the damage to Chip devices, so advised that heat of iron should be lower than 15W with temperature control under 5 seconds at 230-260 deg. C. (The device would be got damage in re working process, recommended under 5 seconds at 230-260 deg. C)
- 5. All equipment and machinery must be properly grounded. It is recommended to use a wristband or anti-electrostatic glove when handing the LED.
- 6. Use IPA as a solvent for cleaning the LED. The other solvent may dissolve the LED package and the epoxy, Ultrasonic cleaning should not be done.
- 7. Damaged LED will show unusual characteristics such as leak current remarkably increase, turn-on voltage becomes lower and the LED get unlight at low current.
- 8. OPTOSUPPLY will not do 4M change without advance consultation.

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